Henkel Solutions for Leadframe Packaging
Die Attach Films

DIE ATTACH FILMS FOR WIREBOND LEADFRAME PACKAGING

- Logic IC, MOSFET and RF
  - Electrically Conductive
    - LOCTITE ABLESTIK CDF 200P Series
    - LOCTITE ABLESTIK CDF 300P Series
    - LOCTITE ABLESTIK CDF 500P Series
  - Electrically Non-conductive
    - LOCTITE ABLESTIK CDF 600P Series
    - LOCTITE ABLESTIK CDF 700P Series
    - LOCTITE ABLESTIK CDF 800P Series

- QFN
  - Electrically Non-conductive
    - LOCTITE ABLESTIK ATB 100 Series
    - LOCTITE ABLESTIK ATB 100HA Series
    - LOCTITE ABLESTIK ATB F100E Series

- QFP
  - Electrically Non-conductive
    - LOCTITE ABLESTIK ATB 100 Series
    - LOCTITE ABLESTIK ATB 100HA Series
    - LOCTITE ABLESTIK ATB F100E Series

- SOIC, TSOP and TSSOP
  - Electrically Non-conductive
    - LOCTITE ABLESTIK ATB 100US Series
    - LOCTITE ABLESTIK ATB 100U Series

The information provided herein, especially recommendations for the usage and the application of our products, is based upon our knowledge and experience. Due to different materials used as well as to varying working conditions beyond our control we strictly recommend to carry out intensive trials to test the suitability of our products with regard to the required processes and applications. We do not accept any liability with regard to the above information or with regard to any verbal recommendation, except for cases where we are liable of gross negligence or false intention. The information is protected by copyright. In particular, any reproductions, adaptations, translations, storage and processing in other media, including storage or processing by electronic means, enjoy copyright protection. Any exploitation in whole or in part thereof shall require the prior written consent of Henkel AG & Co. KGaA. Except as otherwise noted, all marks used in this document are trademarks and/or registered trademarks of Henkel and/or its affiliates in the US, Germany, and elsewhere. © Henkel AG & Co. KGaA, 02/2018
### Henkel Solutions for Leadframe Packaging

#### Die Attach Films

**ELECTRICALLY CONDUCTIVE DIE ATTACH FILMS (CDAF)**

<table>
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<tr>
<th>PRODUCT</th>
<th>DESCRIPTION</th>
<th>KEY ATTRIBUTES</th>
<th>FILM THICKNESS (μm)</th>
<th>MOISTURE SENSITIVITY LEVEL, MSL</th>
<th>THERMAL CONDUCTIVITY (W/m·K)</th>
<th>IN-PACKAGE THERMAL RESISTANCE (K/W)</th>
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| LOCTITE ABLESTIK CDF 200P Series | Ag-filled die attach adhesive | • Suitable for small die  
• Recommended for thin wafer handling applications  
• Oven cure | 15 or 30 | L1 260°C capable | 2.3 | 1.5 |
| LOCTITE ABLESTIK CDF 300P Series | Ag-filled die attach adhesive | • Suitable for small die  
• High adhesion  
• Good wetting  
• Oven cure | 15 or 30 | L1 260°C capable | 1.0 | 2.1 |
| LOCTITE ABLESTIK CDF 500P Series | Ag-filled die attach adhesive | • Suitable for medium to large dies  
• Good wetting and low warpage  
• Recommended for thin wafer handling applications  
• Oven cure | 15 or 30 | L1 260°C capable | 1.5 | 1.4 |
| LOCTITE ABLESTIK CDF 600P Series | Ag-filled die attach adhesive | • Low stress and excellent wetting for large die  
• Compatible with various metal surfaces, including solder  
• Recommended for thin wafer handling applications  
• Oven cure | 25 | L2 260°C capable | 1.0 | 2.1 |
| LOCTITE ABLESTIK CDF 700P Series | Ag-filled die attach adhesive | • Suitable for small and medium die  
• High adhesion  
• Oven cure | 15 or 30 | L1 260°C capable | 5.5 | 0.7 |
| LOCTITE ABLESTIK CDF 800P Series | Ag-filled die attach adhesive | • Suitable for small die  
• Recommended for thin wafer handling applications  
• Oven cure | 15 | L1 260°C capable | 3.4 | 0.7 |

**ELECTRICALLY NON-CONDUCTIVE DICING DIE ATTACH FILMS (DDF)**

<table>
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<tr>
<th>PRODUCT</th>
<th>DESCRIPTION</th>
<th>KEY ATTRIBUTES</th>
<th>DICING TAPE</th>
<th>FILM THICKNESS (μm)</th>
<th>WAFER THICKNESS (μm)</th>
<th>MOISTURE SENSITIVITY LEVEL, MSL</th>
<th>MODULUS AT 25°C (MPa)</th>
</tr>
</thead>
</table>
| LOCTITE ABLESTIK ATB 100 Series | Silica-filled, rubberized epoxy die attach adhesive | • Compatible with Cu wire or Au wire packages  
• Excellent wetting  
• Compatible with Stealth Dicing Before Grind (SDBG) process  
• Oven cure | Non-UV | 15, 20, 25 or 30 | ≥ 75 | L2 260°C capable | 1,170 |
| LOCTITE ABLESTIK ATB 100HA Series | Silica-filled, epoxy die attach adhesive | • Consistent dicing and die pickup for large die applications  
• No passivation damage  
• Compatible with Stealth Dicing Before Grind (SDBG) process  
• SkipCure | UV/Non-UV | 5, 10, 15, 20, 25 or 30 | ≥ 50 | L1 260°C capable | 2,299 |
| LOCTITE ABLESTIK ATB 100U Series | Silica-filled, rubberized epoxy die attach adhesive | • Compatible with Cu wire or Au wire packages  
• No passivation damage  
• Compatible with Stealth Dicing Before Grind (SDBG) process  
• Fast oven cure | Non-UV | 5, 10, 15, 20, 25 or 30 | ≥ 75 | L2 260°C capable | 875 |
| LOCTITE ABLESTIK ATB 100US Series | Silica-filled, epoxy die attach adhesive | • Consistent dicing and die pickup for large die applications  
• No passivation damage  
• Long thermal budget (4 hr. at 175°C)  
• SkipCure during molding process | UV/Non-UV | 5, 10, 15, 20, 25 or 30 | ≥ 50 | L2 260°C capable | 1,277 |
| LOCTITE ABLESTIK ATB F100E Series | Silica-filled, epoxy die attach adhesive | • Suitable for small to large die  
• Excellent workability for below 3 mm x 3 mm die  
• Long work life (4 months before and after lamination)  
• Compatible with Stealth Dicing Before Grind (SDBG) process  
• Film on wire (FoW) and film over die (FoD) applications  
• Oven cure | UV/Non-UV | 25 FoW: 35 – 80  
FoD: 90 – 150 | ≥ 75 | L1 260°C capable | 5,256 |